

IN THE SPECIFICATION

Please replace Paragraph [0003] with the following amended paragraph:

[0003] Semiconductor packages ~~which that~~ comprise a leadframe that includes a central platform to which an integrated-chip ~~is connected~~ are known. These types of semiconductor packages are generally fabricated with radiating external electrical connection leads connected at a fixed distance from the central platform and generally connected to the integrated-chip via electrical connection wires.

Please replace Paragraph [0004] with the following amended paragraph:

[0004] These ~~type types~~ of semiconductor ~~package packages~~ although useful, have their shortcomings. One shortcoming is the complexity to fabricate the chip. Accordingly, a need exists to overcome the complexity to ~~fabricated semiconductor~~ ~~fabricate semiconductor packages~~ with lead lines attached to integrated circuits.

Please replace Paragraph [0016] with the following amended paragraph:

[0016] According to the invention, the encapsulation block may comprise a peripheral annular part extending ~~fowards forward~~, around and at a certain distance from the ~~[[plate, a]] plate~~. A ring made of a filling material ~~filling fills~~ the space that separates the periphery of the plate from the peripheral annular part.

Please replace Paragraph [0044] with the following amended paragraph:

[0044] This package body 21 comprises a rear wall 22, that which has a rear face 23 and a front face 24, and a forward projecting peripheral wall 25 forming an annular wall.

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Please replace Paragraph [0044] with the following amended paragraph:

[0044] This package body 21 comprises a rear wall 22, ~~that which~~ has a rear face 23 and a front face 24, and a forward projecting peripheral wall 25 forming an annular wall.

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